# ABSOLUTE MAXIMUM RATING

Symbol	Parameter		Value		Unit	
		PowerSO-10 D2PAK	SOT-82FM	ISOWATT220		
VDS	Drain-source Voltage (V <sub>in</sub> = 0)	Internally Clamped				
$V_{\text{in}}$	Input Voltage		18			
ID	Drain Current	li	Internally Limited			
I <sub>R</sub>	Reverse DC Output Current	-14				
$V_{\text{esd}}$	Electrostatic Discharge (C= 100 pF, R=1.5 K $\Omega$ )		2000		V	
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	50	9.5	31	W	
Tj	Operating Junction Temperature	Internally Limited				
Tc	Case Operating Temperature	Internally Limited				
T <sub>stg</sub>	Storage Temperature		-55 to 150		°C	

# THERMAL DATA

			ISOWATT220	PowerSO-10	SOT82-FM	D2PAK	
$R_{thj-case}$	Thermal Resistance Junction-case	Мах	4	2.5	13	2.5	°C/W
$R_{thj-amb}$	Thermal Resistance Junction-ambient	Мах	62.5	50	100	62.5	°C/W

# **ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25 \ ^{o}C$ unless otherwise specified) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>CLAMP</sub>	Drain-source Clamp Voltage	$I_D = 200 \text{ mA}$ $V_{in} = 0$	60	70	80	V
V <sub>CLTH</sub>	Drain-source Clamp Threshold Voltage	$I_D = 2 \text{ mA}  V_{in} = 0$	55			V
VINCL	Input-Source Reverse Clamp Voltage	l <sub>in</sub> = -1 mA	-1		-0.3	V
I <sub>DSS</sub>	Zero Input Voltage Drain Current (V <sub>in</sub> = 0)				50 200	μΑ μΑ
l <sub>ISS</sub>	Supply Current from Input Pin	$V_{DS} = 0 \ V \qquad V_{in} = 10 \ V$		250	500	μA

#### ON (\*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
VIN(th)	Input Threshold Voltage	$V_{DS} = V_{in}$ $I_D + I_{in} = 1 \text{ mA}$	0.8		3	V
$R_{\text{DS(on)}}$	Static Drain-source On Resistance	$V_{in} = 10 V I_D = 5 A$ $V_{in} = 5 V I_D = 5 A$			0.1 0.14	Ω Ω

57

# ELECTRICAL CHARACTERISTICS (continued)

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	$V_{DS} = 13 V$ $I_D = 5 A$	6	8		S
Coss	Output Capacitance	$VDS = 13 V  f = 1 MHz  V_{in} = 0$		350	500	pF

# SWITCHING (\*\*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
td(on)	Turn-on Delay Time	V <sub>DD</sub> = 15 V I <sub>d</sub> = 5 A		50	100	ns
tr	Rise Time	$V_{gen} = 10 V$ $R_{gen} = 10 \Omega$		80	160	ns
t <sub>d(off)</sub>	Turn-off Delay Time	(see figure 3)		230	400	ns
t <sub>f</sub>	Fall Time			100	180	ns
t <sub>d(on)</sub>	Turn-on Delay Time	$V_{DD} = 15 V$ $I_d = 5 A$		600	900	ns
tr	Rise Time	$V_{gen} = 10 V$ $R_{gen} = 1000 \Omega$		0.9	2	μs
t <sub>d(off)</sub>	Turn-off Delay Time	(see figure 3)		3.8	6	μs
t <sub>f</sub>	Fall Time			1.7	2.5	μs
(di/dt) <sub>on</sub>	Turn-on Current Slope	$V_{DD} = 15 V$ $I_D = 5 A$		60		A/μs
		$V_{in} = 10 V$ $R_{gen} = 10 \Omega$				
Qi	Total Input Charge	$V_{DD} = 12 \text{ V}  I_D = 5 \text{ A}  V_{in} = 10 \text{ V}$		30		nC

# SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>SD</sub> (*)	Forward On Voltage	$I_{SD} = 5 A  V_{in} = 0$			1.6	V
t <sub>rr</sub> (**)	Reverse Recovery Time	$I_{SD} = 5 A$ di/dt = 100 A/µs V <sub>DD</sub> = 30 V $T_i = 25 \ ^{\circ}C$		125		ns
Qrr (**)	Reverse Recovery Charge	(see test circuit, figure 5)		0.3		μC
I <sub>RRM</sub> (**)	Reverse Recovery Current			4.8		A

# PROTECTION

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
l <sub>lim</sub>	Drain Current Limit		7 7	10 10	14 14	A A
t <sub>dlim</sub> (**)	Step Response Current Limit	V <sub>in</sub> = 10 V V <sub>in</sub> = 5 V		20 50	30 80	μs μs
T <sub>jsh</sub> (**)	Overtemperature Shutdown		150			°C
T <sub>jrs</sub> (**)	Overtemperature Reset		135			°C
l <sub>gf</sub> (**)	Fault Sink Current			50 20		mA mA
E <sub>as</sub> (**)	Single Pulse Avalanche Energy	starting T <sub>j</sub> = 25 $^{\circ}$ C V <sub>DD</sub> = 20 V V <sub>in</sub> = 10 V R <sub>gen</sub> = 1 K $\Omega$ L = 10 mH	0.4			J

(\*) Pulsed: Pulse duration =  $300 \,\mu$ s, duty cycle 1.5 % (\*\*) Parameters guaranteed by design/characterization

57

#### **PROTECTION FEATURES**

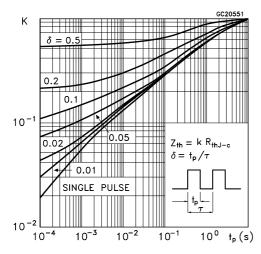
During normal operation, the Input pin is electrically connected to the gate of the internal power MOSFET. The device then behaves like a standard power MOSFET and can be used as a switch from DC to 50 KHz. The only difference from the user's standpoint is that a small DC current ( $I_{\rm ISS}$ ) flows into the Input pin in order to supply the internal circuitry.

The device integrates:

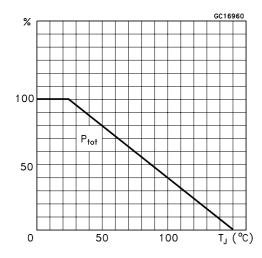
- OVERVOLTAGE CLAMP PROTECTION: internally set at 70V, along with the rugged avalanche characteristics of the Power MOSFET stage give this device unrivalled ruggedness and energy handling capability. This feature is mainly important when driving inductive loads.
- LINEAR CURRENT LIMITER CIRCUIT: limits the drain current ld to llim whatever the Input pin voltage. When the current limiter is active, the device operates in the linear region, so power dissipation may exceed the capability of the heatsink. Both case and junction temperatures increase, and if this phase lasts long enough, junction temperature may reach the overtemperature threshold T<sub>jsh</sub>.
- OVERTEMPERATURE AND SHORT CIRCUIT PROTECTION: these are based on sensing the chip temperature and are not dependent on the input voltage. The location of the sensing element on the chip in the power stage area ensures fast, accurate detection of the junction temperature. Overtemperature cutout occurs at minimum 150°C. The device is automatically restarted when the chip temperature falls below 135°C.
- STATUS FEEDBACK: In the case of an overtemperature fault condition, a Status Feedback is provided through the Input pin. The internal protection circuit disconnects the input from the gate and connects it instead to ground via an equivalent resistance of 100  $\Omega$ . The failure can be detected by monitoring the voltage at the Input pin, which will be close to ground potential.

Additional features of this device are ESD protection according to the Human Body model and the ability to be driven from a TTL Logic circuit (with a small increase in R<sub>DS(on)</sub>).

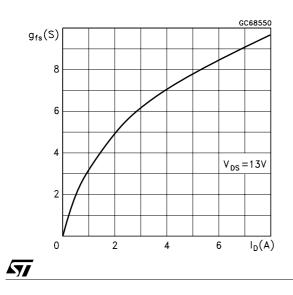
#### Thermal Impedance For ISOWATT220



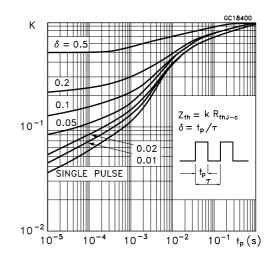
#### **Derating Curve**



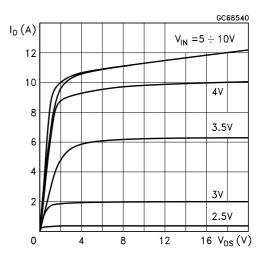
#### Transconductance



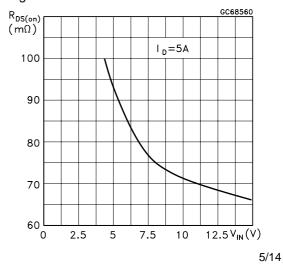
#### Thermal Impedance For D2PAK / PowerSO-10

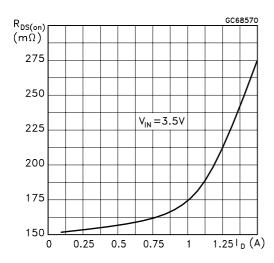


#### **Output Characteristics**



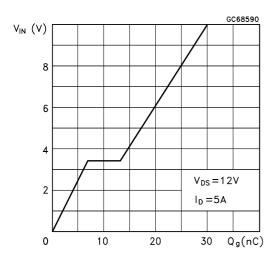
Static Drain-Source On Resistance vs Input Voltage



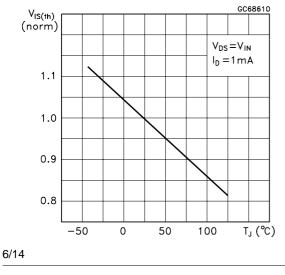


#### Static Drain-Source On Resistance

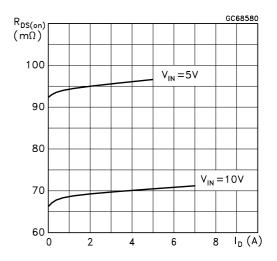
## Input Charge vs Input Voltage



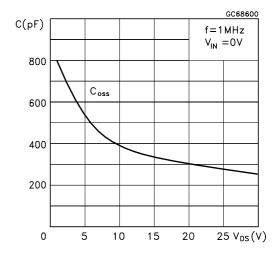
Normalized Input Threshold Voltage vs Temperature



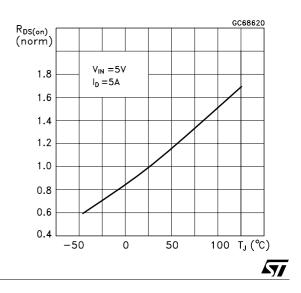
# Static Drain-Source On Resistance

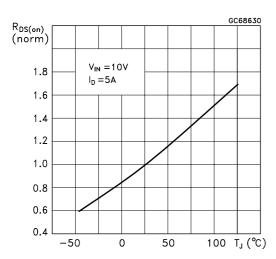


#### Capacitance Variations



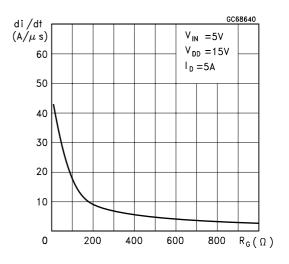
#### Normalized On Resistance vs Temperature

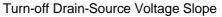


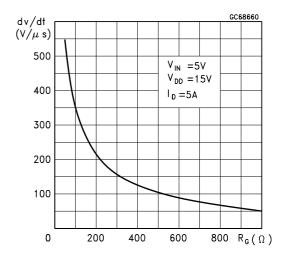


#### Normalized On Resistance vs Temperature

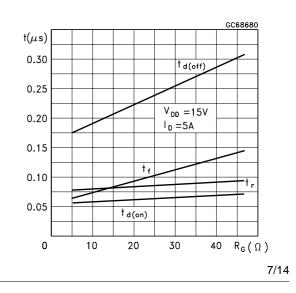
Turn-on Current Slope



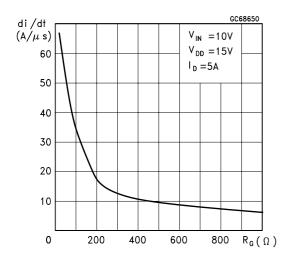


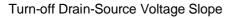


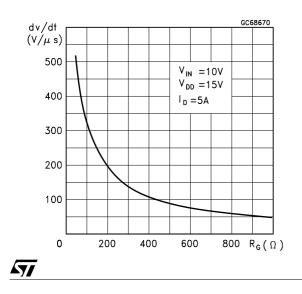




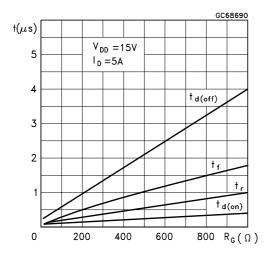
# Turn-on Current Slope



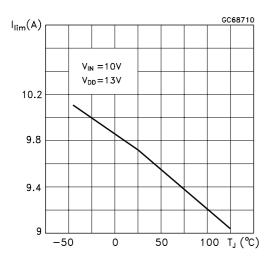




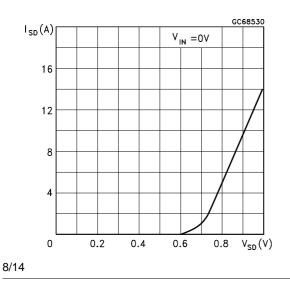
#### Switching Time Resistive Load



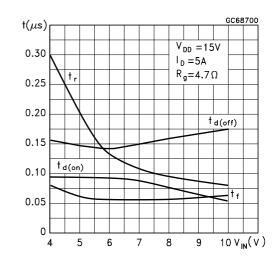
Current Limit vs Junction Temperature

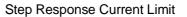


# Source Drain Diode Forward Characteristics



Switching Time Resistive Load





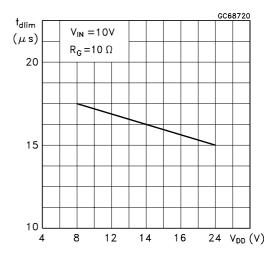
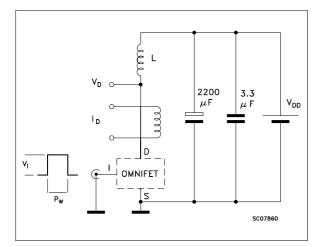
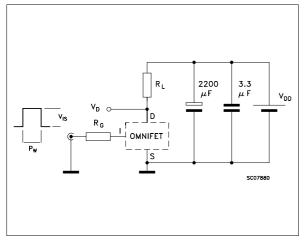




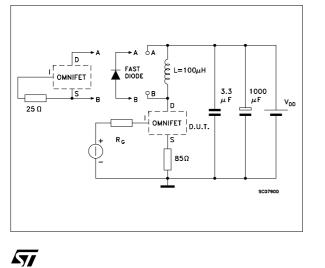
Fig. 1: Unclamped Inductive Load Test Circuits



**Fig. 3:** Switching Times Test Circuits For Resistive Load



**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times



# Fig. 2: Unclamped Inductive Waveforms

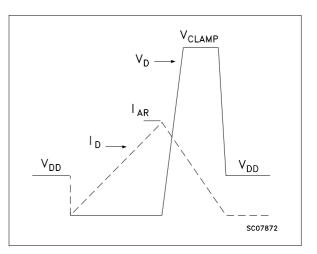


Fig. 4: Input Charge Test Circuit

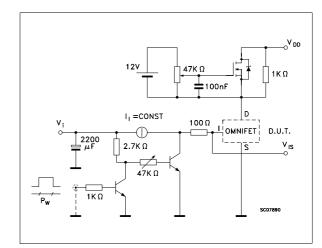
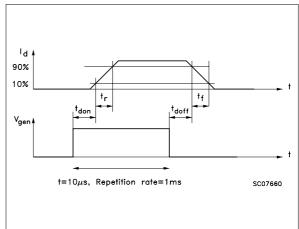
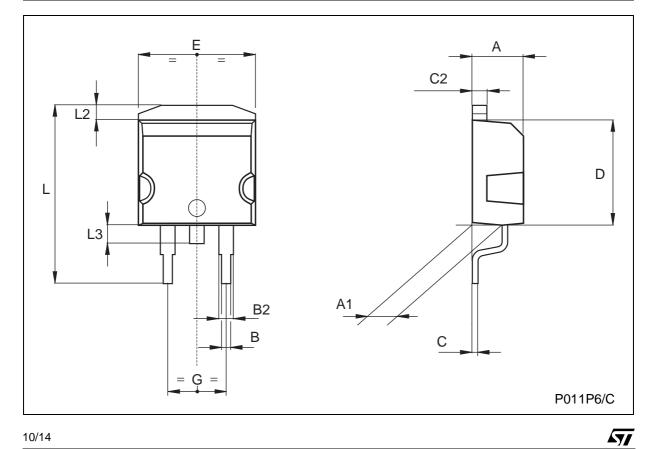


Fig. 6: Waveforms



DIM.		mm			inch	
Dim	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.3		4.6	0.169		0.181
A1	2.49		2.69	0.098		0.106
В	0.7		0.93	0.027		0.036
B2	1.25		1.4	0.049		0.055
С	0.45		0.6	0.017		0.023
C2	1.21		1.36	0.047		0.053
D	8.95		9.35	0.352		0.368
Е	10		10.28	0.393		0.404
G	4.88		5.28	0.192		0.208
L	15		15.85	0.590		0.624
L2	1.27		1.4	0.050		0.055
L3	1.4		1.75	0.055		0.068

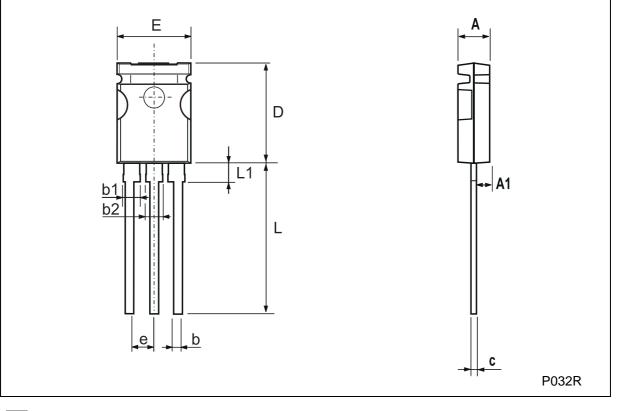
# TO-263 (D2PAK) MECHANICAL DATA



10/14

DIM		mm			inch	
DIM.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	2.85		3.05	1.122		1.200
A1	1.47		1.67	0.578		0.657
b	0.40		0.60	0.157		0.236
b1	1.4		1.6	0.551		0.630
b2	1.3		1.5	0.511		0.590
С	0.45		0.6	0.177		0.236
D	10.5		10.9	4.133		4.291
е	2.2		2.8	0.866		1.102
E	7.45		7.75	2.933		3.051
L	15.5		15.9	6.102		6.260
L1	1.95		2.35	0.767		0.925

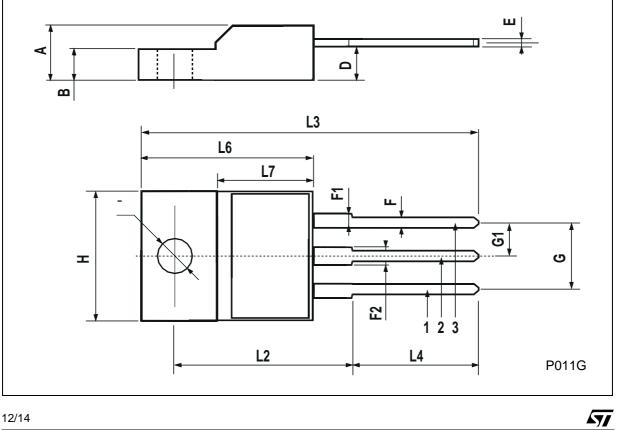






DIM.		mm			inch	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.4		0.7	0.015		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126

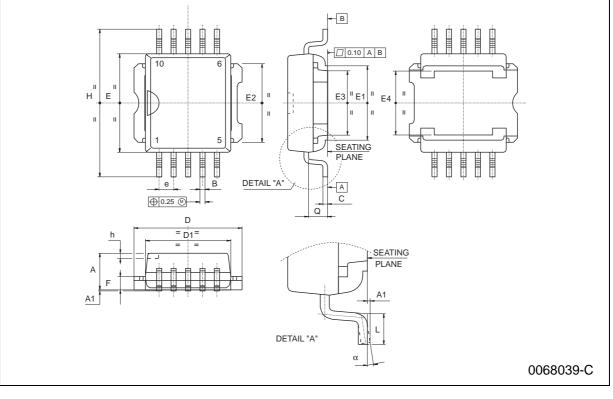




12/14

DIM.		mm			inch	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	3.35		3.65	0.132		0.144
A1	0.00		0.10	0.000		0.004
В	0.40		0.60	0.016		0.024
С	0.35		0.55	0.013		0.022
D	9.40		9.60	0.370		0.378
D1	7.40		7.60	0.291		0.300
Е	9.30		9.50	0.366		0.374
E1	7.20		7.40	0.283		0.291
E2	7.20		7.60	0.283		0.300
E3	6.10		6.35	0.240		0.250
E4	5.90		6.10	0.232		0.240
е		1.27			0.050	
F	1.25		1.35	0.049		0.053
Н	13.80		14.40	0.543		0.567
h		0.50			0.002	
L	1.20		1.80	0.047		0.071
q		1.70			0.067	
α	0 <sup>o</sup>		8°			





**57** 

#### Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries. Information in this document supersedes and replaces all information previously supplied. The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2013 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com



DocID1642 Rev 6